

Title (en)

PROCESS AND APPARATUS FOR REGENERATING AN ELECTROLESS COPPER-PLATING BATH

Publication

**EP 0240589 B1 19900207 (DE)**

Application

**EP 86105002 A 19860411**

Priority

EP 86105002 A 19860411

Abstract (en)

[origin: US4734175A] A process and an apparatus are described for regenerating an electroless copper plating bath containing a complexing agent, preferably ethylenediamine tetraacetic acid. From the bath solution to be regenerated, the copper content is reduced by electrolysis to a value below 20 mg/l and the complexing agent subsequently precipitated by acidification and recovered. After dissolution in an alkaline electrolytic solution, the solution thus obtained is fed back to the electroless copper plating bath. A particularly pure ethylenediamine tetraacetic acid free from by-products is obtained if the pH value is kept constant during electrolysis, an anodic current density  $i_+$  of 100 A/m<sup>2</sup> is not exceeded, and the anodic current density during electrolysis is reduced according to the electrolysis characteristic or in steps.

IPC 1-7

**C23C 18/16**

IPC 8 full level

**C23C 18/16** (2006.01); **C23C 18/40** (2006.01)

CPC (source: EP US)

**C23C 18/1617** (2013.01 - EP US)

Cited by

WO2013191554A2

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

**EP 0240589 A1 19871014**; **EP 0240589 B1 19900207**; DE 3668914 D1 19900315; JP H0236677 B2 19900820; JP S62243776 A 19871024; US 4734175 A 19880329

DOCDB simple family (application)

**EP 86105002 A 19860411**; DE 3668914 T 19860411; JP 3596387 A 19870220; US 3338787 A 19870402